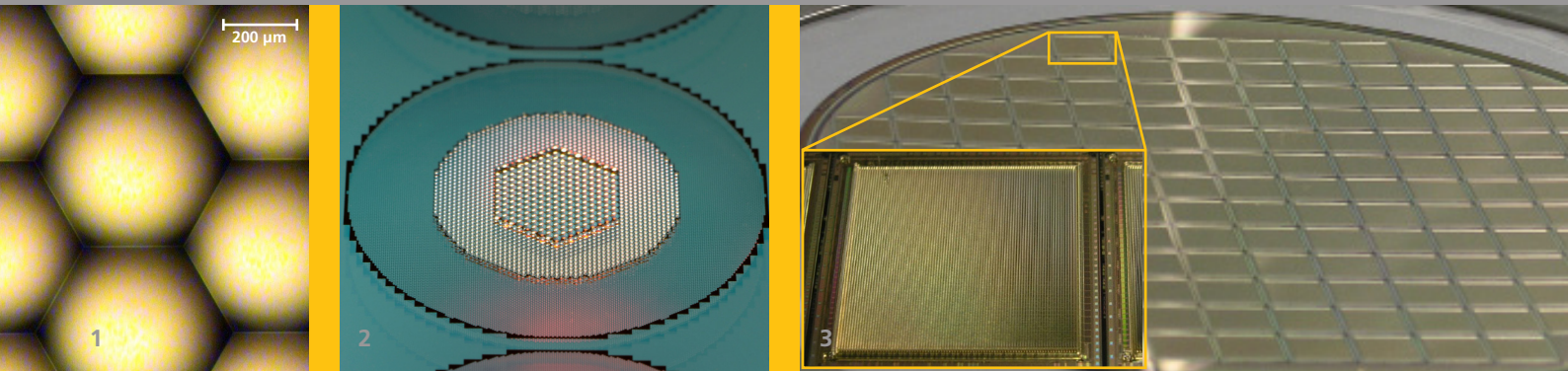




1 Detail of high fill factor lens array mastered by lithography, reflow and RIE.

2 Double sided beam homogenizer with 3 different zones NA 0.1, 0.2, 0.3, and buried aperture array.

3 Si CMOS wafer with lens arrays on top of the detector area by selective UV curing.

MICROLENS ARRAYS

Objective

Reproducible fabrication of refractive microlenses with parameters derived from system design calculations.

Technology

- Mastering by lithography and reflow
- Replication by UV polymer molding or
- Transfer to silicon, glass or fused silica by reactive ion etching
- AR-coating, dicing
- Integration of aperture-/filter structures
- Double-sided patterning (tandem arrays)

Geometry of the lens arrays

- Spherical, cylindrical or elliptical lenslets; sag up to 100 μm
- Layout and focal length varying across the array or wafer ("Chirp")
- Lens diameter: 5 μm – 3000 μm

- Resolution/lens gap: 1 μm
- High fill factor, lateral precision
- Homogeneity of focal lengths +1% across wafer
- Generation of aspheres by reactive ion etching (RIE)
- 100% fill factor of arrays by RIE assisted mastering

Replication by UV molding

- As thin polymer layer on glass, Si, etc.
- High lateral and axial precision
- High chemical/thermal stability
- On top of processed wafers (CMOS, VCSEL)

Applications

- Laser/fiber collimation
- Beam forming elements, homogenizer
- Fill factor enhancement on detector arrays
- Field-of-view matching for displays
- Miniaturized imaging systems, sensors

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